

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-19 (Canceled)

20. (Previously Presented) A semiconductor device comprising:
a semiconductor chip;
a first metallic member connected to a main current electrode on a circuit forming front plane of the chip; and
a second metallic member connected to a chip rear plane electrode;
a third metallic member connected to a control electrode on the front plane of the chip; wherein:
said main current electrode and said control electrode are composed of any of an Al film and an Al alloy film;
plural Au bumps are formed on the Al electrode film in a metallically bonded condition;
each of said first and second metallic members, which are plated with a precious metal, has such a structure that each is bonded with said Au bumps by compression bonding, and gaps between the metallic members and said chip are filled with resin; and
a plane of said second metallic member opposite to said chip in a plan view projected direction of the chip, and planes of said first and third metallic members opposite to said chip are exposed to the surface of said semiconductor device.

Claims 21-24 (Canceled).

25. (Previously Presented) A semiconductor device comprising:

 a semiconductor chip;

 a first metallic member connected to a main current electrode on a circuit forming front plane of the chip; and

 a second metallic member connected to a chip rear plane electrode;

 a third metallic member connected to a control electrode on the front plane of the chip; wherein:

 said main current electrode and said control electrode are composed of any of an Al film and an Al alloy film;

 plural Au bumps are formed on the Al electrode film in a metallically bonded condition;

 each of said first and second metallic members, which are plated with a precious metal, has such a structure that each is bonded with said Au bumps by compression bonding, and gaps between the metallic members and said chip are filled with resin; and

 a plane of said second metallic member opposite to said chip in a plan view projected direction of the chip is exposed to the surface of said semiconductor device.